

Date: 4/16/2021

Material Number: SI82394AB4-IS1

Pkg Config.: PK1213

Detailed Device Composition 									
No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Mold Compound	107.36	Carbon Black	1333-86-4	0.300	0.322	3000	0.1896	1896
			Epoxy Resin (Proprietary)	Proprietary	8.000	8.589	80000	5.0573	50573
			Phenol Resin (Proprietary)	Proprietary	5.700	6.120	57000	3.6033	36033
			Silicon Dioxide	60676-86-0	86.000	92.330	860000	54.3659	543659
2	Leadframe	59.77	Copper	7440-50-8	96.190	57.493	961900	33.8531	338531
			Gold	7440-57-5	0.020	0.012	200	0.0070	70
			Iron	7439-89-6	2.250	1.345	22500	0.7919	7919
			Nickel	7440-02-0	1.250	0.747	12500	0.4399	4399
			Palladium	7440-05-3	0.050	0.030	500	0.0176	176
			Phosphorous	7723-14-0	0.100	0.060	1000	0.0352	352
			Silver	7440-22-4	0.020	0.012	200	0.0070	70
			Zinc	7440-66-6	0.120	0.072	1200	0.0422	422
3	Die Attach Epoxy	0.20	2-Ethylhexyl Glycidyl Ether	2461-15-6	7.000	0.014	70000	0.0082	82
			Bisphenol F	620-92-8	12.000	0.024	120000	0.0141	141
			Epoxy Acrylate	15625-89-5	15.000	0.030	150000	0.0177	177
			Silver	7440-22-4	65.000	0.130	650000	0.0765	765
			Substituted Polyamine	68490-66-4	1.000	0.002	10000	0.0012	12
4	Bond Wire	0.31	Gold	7440-57-5	99.000	0.307	990000	0.1807	1807
			Palladium	7440-05-3	1.000	0.003	10000	0.0018	18
5	Die	0.73	Aluminum	7429-90-5	0.163	0.001	1630	0.0007	7
			Copper	7440-50-8	0.001	0.000	10	0.0000	0
			Silicon	7440-21-3	99.726	0.728	997260	0.4287	4287
			Tungsten	7440-33-7	0.110	0.001	1100	0.0005	5
6	Die	1.46	Aluminum	7429-90-5	0.163	0.002	1630	0.0014	14
			Copper	7440-50-8	0.001	0.000	10	0.0000	0
			Silicon	7440-21-3	99.726	1.456	997260	0.8573	8573
			Tungsten	7440-33-7	0.110	0.002	1100	0.0009	9
	Total Unit Weight =	169.83				169.83		100.0000	1000000